

# **Product Change Notification / GBNG-28ZDD0521**

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01-Feb-2021

# **Product Category:**

Power Management - System Supervisors/Voltage Detectors

# **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 3788.002 Final Notice: Qualification of Lintec backside coating (BSC) material for selected Micrel MIC2782xxx device family available in 6L WLCSP (1.2x0.8x0.63mm) package at UAT assembly site.

# **Affected CPNs:**

GBNG-28ZDDO521\_Affected\_CPN\_02012021.pdf GBNG-28ZDDO521\_Affected\_CPN\_02012021.csv

# **Notification Text:**

### **PCN Status:**

Final notification

#### **PCN Type:**

Manufacturing Change

#### Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of Lintec backside coating (BSC) material for selected Micrel MIC2782xxx device family available in 6L WLCSP (1.2x0.8x0.63mm) package at UAT assembly site.

### Pre Change:

Using Hysol CG1001 backside coating (BSC) material and 70 um backside coating (BSC) thickness.

#### Post Change:

Using Lintec LC2826H backside coating (BSC) material and 25 um backside coating (BSC) thickness.

### **Pre and Post Change Summary:**

	Pre Change	Post Change	
	Unisem Advance Tech	Unisem Advance Tech	
Assembly Site			
	(UAT)	(UAT)	
Solder Ball Material	SNAC 105 (ball drop)	SNAC 105 (ball drop)	
Solder Ball Size	250 um	250 um	
Solder Ball Pitch	400 um	400 um	
Backside Coating (BSC) Material	Hysol CG1001	Lintec LC2826H	
Backside Coating (BSC) Thickness	70 um	25 um	

#### **Impacts to Data Sheet:**

None

### **Change Impact:**

None

#### Reason for Change:

To improve manufacturability by qualifying Lintec LC2826H backside coating (BSC) material.

## **Change Implementation Status:**

In Progress

### **Estimated First Ship Date:**

February 28, 2021 (date code: 2110)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

#### **Time Table Summary:**

	February 2021					
Workweek	06	07	08	09	10	
Qual Report Availability	Χ					
Final PCN Issue Date	Χ					
Estimated Implementation Date					Χ	

## Method to Identify Change:

Traceability code

### **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

#### **Revision History:**

**February 01, 2021:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 28, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

PCN\_GBNG-28ZDDO521\_Qual\_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MIC2782CLYCS-TR

MIC2782CRYCS-TR

MIC2782DLYCS-TR

MIC2782DRYCS-TR

MIC2782ELYCS-TR

MIC2782EMYCS-TR

MIC2782FLYCS-TR

MIC2782FRYCS-TR

Date: Monday, February 01, 2021